

## -20V P-Channel Enhancement Mode MOSFET

### Description

The AP2301BI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = -20V$   $I_D = -2.3A$

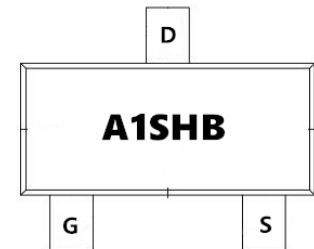
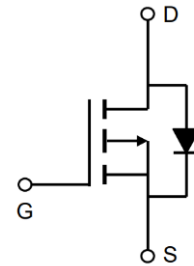
$R_{DS(ON)} < 150m\Omega @ V_{GS} = -4.5V$

### Application

Battery protection

Load switch

Uninterruptible power supply



### Package Marking and Ordering Information

| Product ID | Pack   | Marking | Qty(PCS) |
|------------|--------|---------|----------|
| AP2301BI   | SOT-23 | A1SHB   | 3000     |

### Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise noted)

| Symbol          | Parameter   | Rating     | Units        |
|-----------------|---|------------|--------------|
| $V_{DS}$        | Drain-Source Voltage  | -20        | V            |
| $V_{GS}$        | Gate-Source Voltage   | $\pm 12$   | V            |
| $I_D$           | Drain Current-Continuous                                    | -2.3       | A            |
| $I_{DM}$        | Drain Current -Pulsed <sup>(Note 1)</sup>                   | -10        | A            |
| $P_D$           | Maximum Power Dissipation                                   | 0.7        | W            |
| $T_J, T_{STG}$  | Operating Junction and Storage Temperature Range            | -55 To 150 | $^\circ C$   |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup> | 178        | $^\circ C/W$ |



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### Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

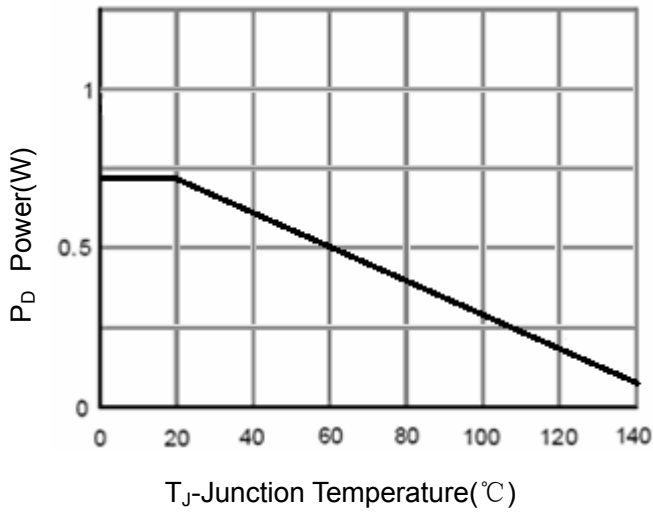
| Symbol              | Parameter                                 | Condition  | Min  | Typ  | Max  | Unit |
|---------------------|---|--|------|------|------|------|
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage            | V <sub>GS</sub> =0V I <sub>D</sub> =-250μA   | -20  |      | -    | V    |
| I <sub>DSS</sub>    | Zero Gate Voltage Drain Current           | V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V   | -    | -    | -1   | μA   |
| I <sub>GSS</sub>    | Gate-Body Leakage Current                 | V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V   | -    | -    | ±100 | nA   |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                    | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA                              | -0.5 | -0.7 | -1.2 | V    |
| R <sub>DS(on)</sub> | Drain-Source On-State Resistance          | V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2 A   | -    | 135  | 165  | mΩ   |
|                     |   | V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-1.8A  | -    | 150  | 185  | mΩ   |
| g <sub>FS</sub>     | Forward Transconductance                  | V <sub>DS</sub> =-5V, I <sub>D</sub> =-2A  | 4    | -    | -    | S    |
| C <sub>ISS</sub>    | Input Capacitance                         | V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V,<br>F=1.0MHz                                | -    | 290  | -    | PF   |
| C <sub>OSS</sub>    | Output Capacitance                        |  | -    | 60   | -    | PF   |
| C <sub>RSS</sub>    | Reverse Transfer Capacitance              |  | -    | 34   | -    | PF   |
| t <sub>d(on)</sub>  | Turn-on Delay Time                        | V <sub>DD</sub> =-10V, R <sub>L</sub> =5Ω V <sub>GS</sub> =-4.5V, R <sub>GEN</sub> =3Ω | -    | 10   | -    | nS   |
| t <sub>r</sub>      | Turn-on Rise Time                         |  | -    | 5.0  | -    | nS   |
| t <sub>d(off)</sub> | Turn-Off Delay Time                       |  | -    | 21   | -    | nS   |
| t <sub>f</sub>      | Turn-Off Fall Time                        |  | -    | 7    | -    | nS   |
| Q <sub>g</sub>      | Total Gate Charge                         | V <sub>DS</sub> =-10V, I <sub>D</sub> =-2A,<br>V <sub>GS</sub> =-4.5V                  | -    | 3.0  | -    | nC   |
| Q <sub>gs</sub>     | Gate-Source Charge                        |  | -    | 0.5  | -    | nC   |
| Q <sub>gd</sub>     | Gate-Drain Charge                         |  | -    | 0.8  | -    | nC   |
| V <sub>SD</sub>     | Diode Forward Voltage <sup>(Note 3)</sup> | V <sub>GS</sub> =0V, I <sub>S</sub> =-2A   | -    | -    | -1.2 | V    |

**Notes:**

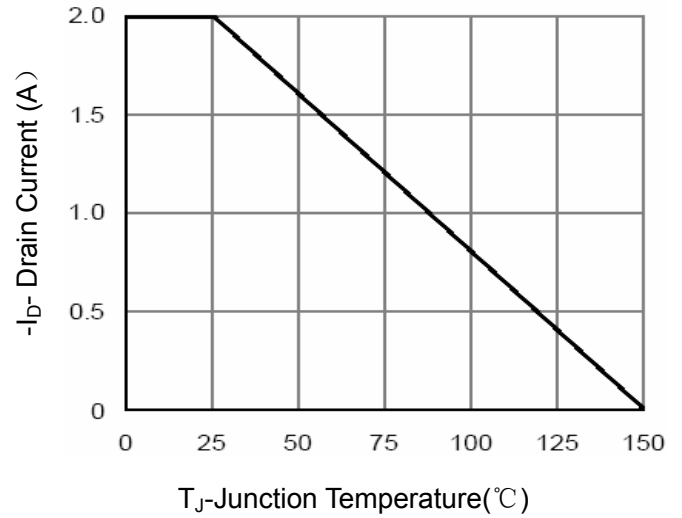
- 1、Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2、Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3、Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- 4、Guaranteed by design, not subject to production

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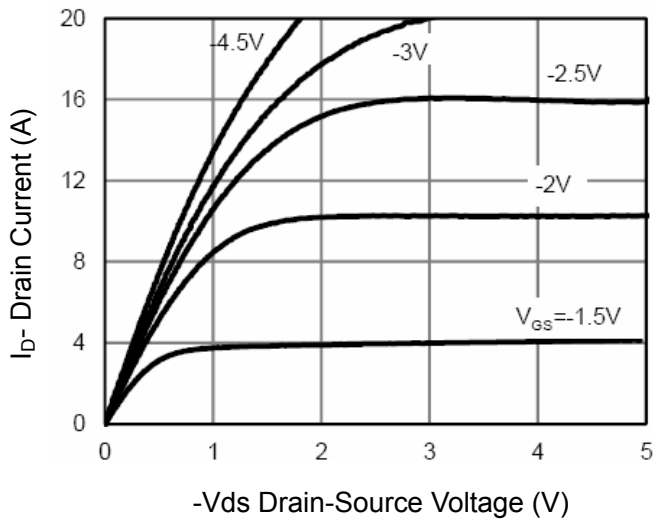
**Typical Characteristics**



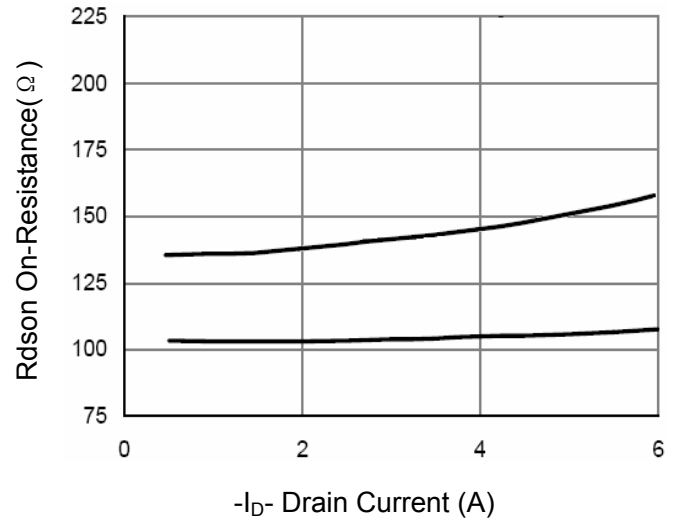
**Figure 1 Power Dissipation**



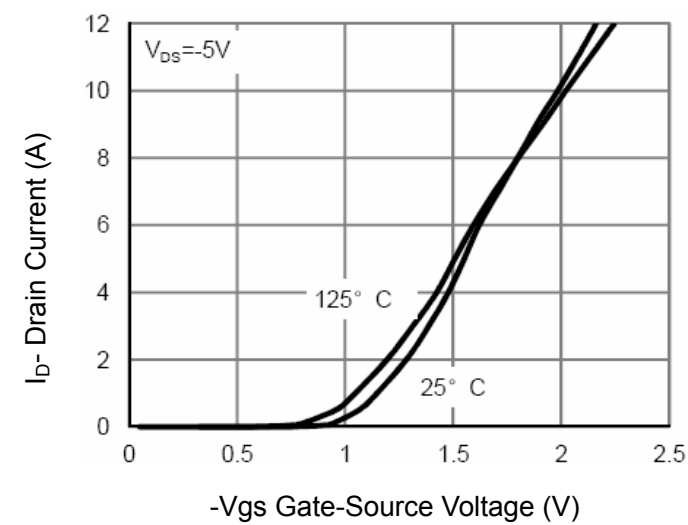
**Figure 2 Drain Current**



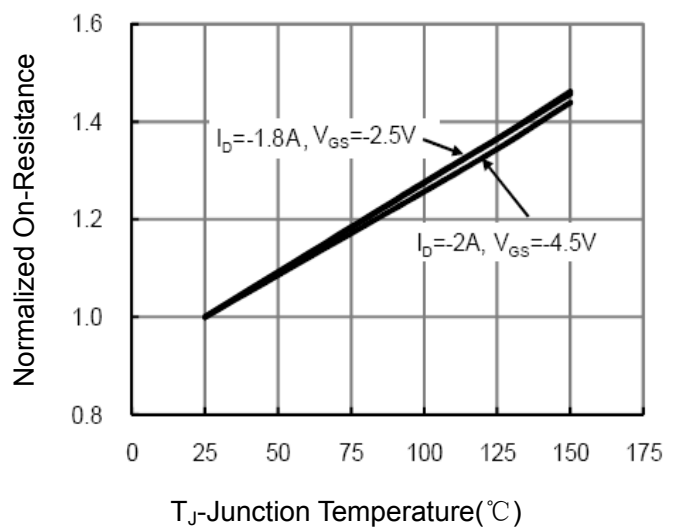
**Figure 3 Output Characteristics**



**Figure 4 Drain-Source On-Resistance**



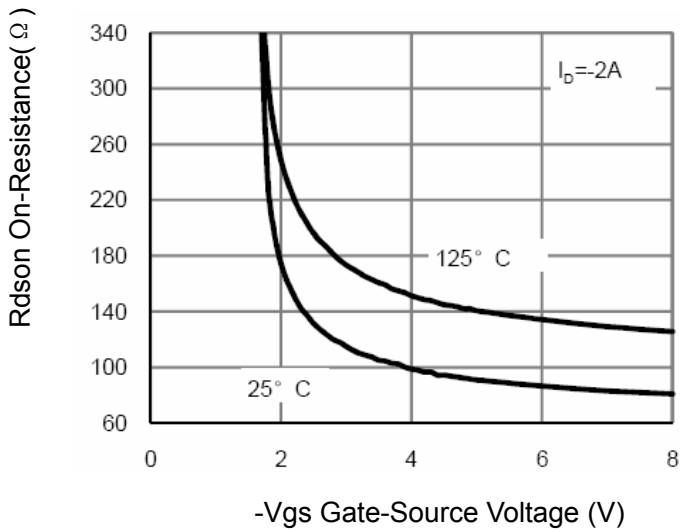
**Figure 5 Transfer Characteristics**



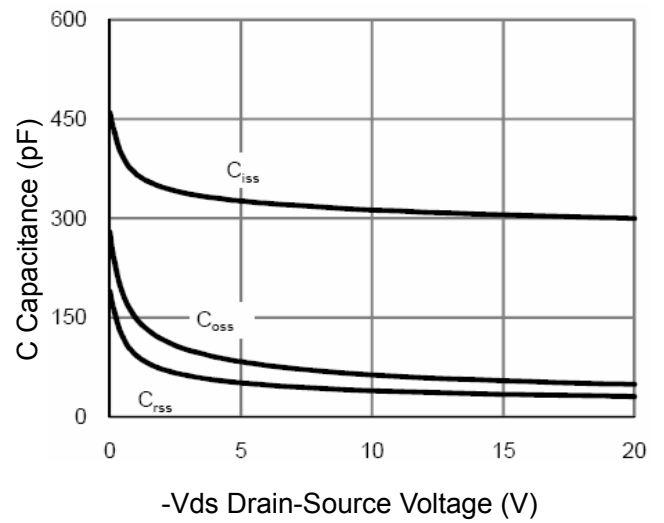
**Figure 6 Drain-Source On-Resistance**



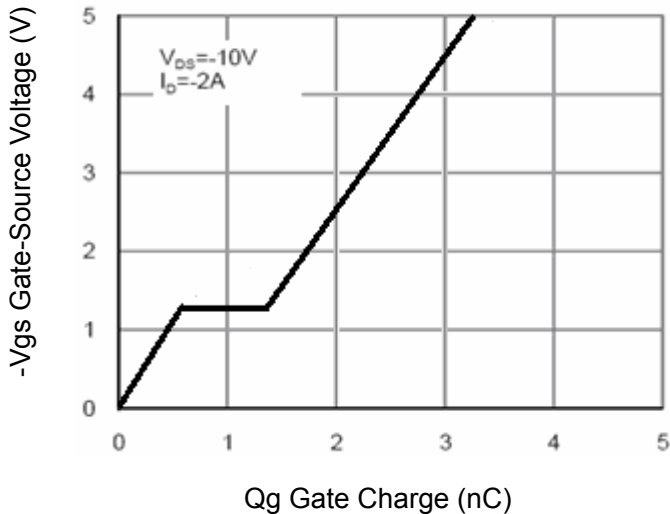
**-20V P-Channel Enhancement Mode MOSFET**



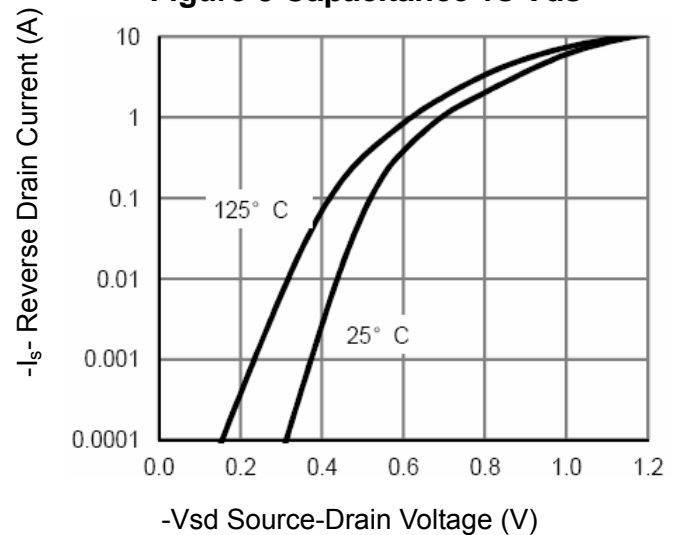
**Figure 7 Rdson vs Vgs**



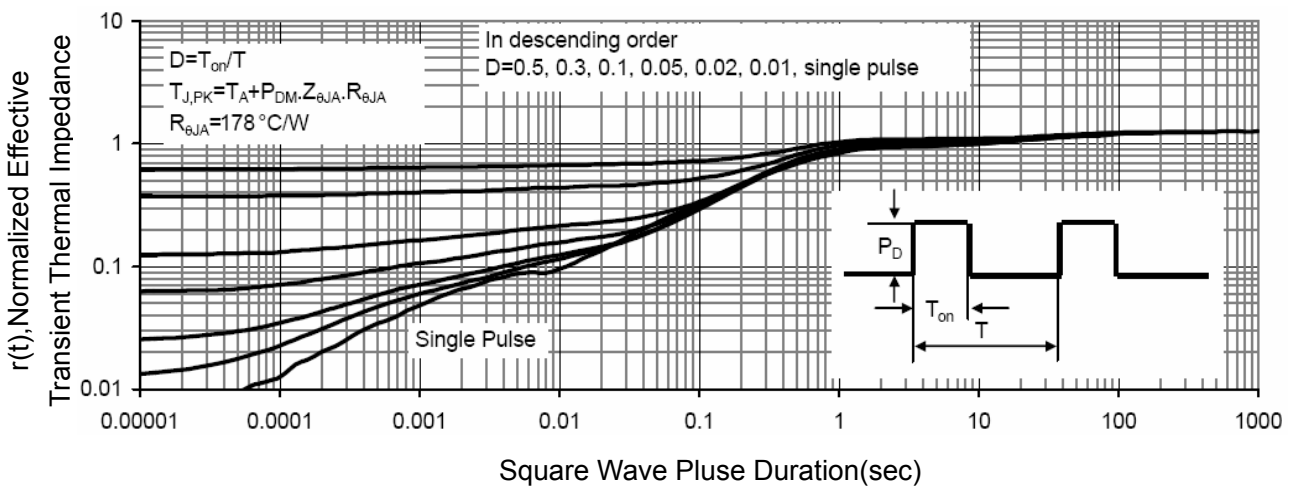
**Figure 8 Capacitance vs Vds**



**Figure 9 Gate Charge**

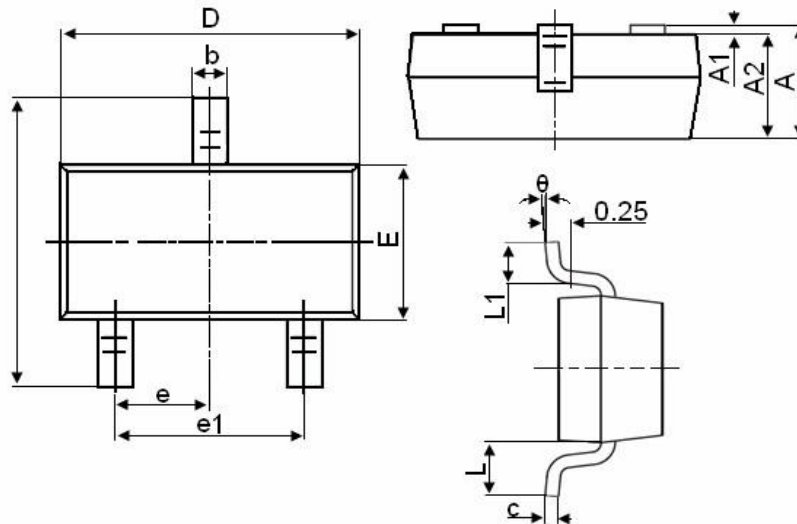


**Figure 10 Source- Drain Diode Forward**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

### Package Mechanical Data:SOT-23



| Symbol   | Dimensions in Millimeters |       |
|----------|---------------------------|-------|
|          | MIN.                      | MAX.  |
| A        | 0.900                     | 1.150 |
| A1       | 0.000                     | 0.100 |
| A2       | 0.900                     | 1.050 |
| b        | 0.300                     | 0.500 |
| c        | 0.080                     | 0.150 |
| D        | 2.800                     | 3.000 |
| E        | 1.200                     | 1.400 |
| E1       | 2.250                     | 2.550 |
| e        | 0.950TYP                  |       |
| e1       | 1.800                     | 2.000 |
| L        | 0.550REF                  |       |
| L1       | 0.300                     | 0.500 |
| $\theta$ | 0°                        | 8°    |

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